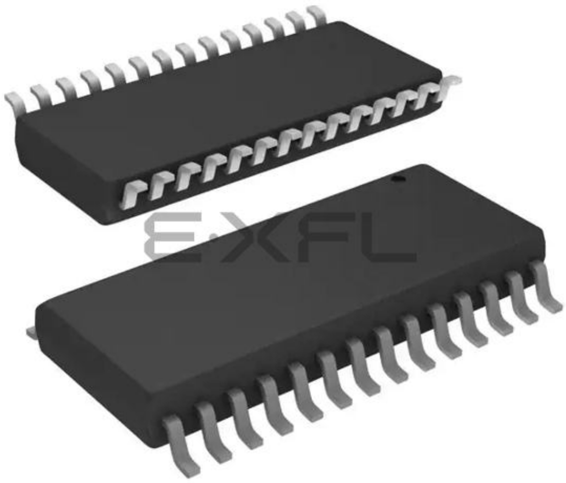

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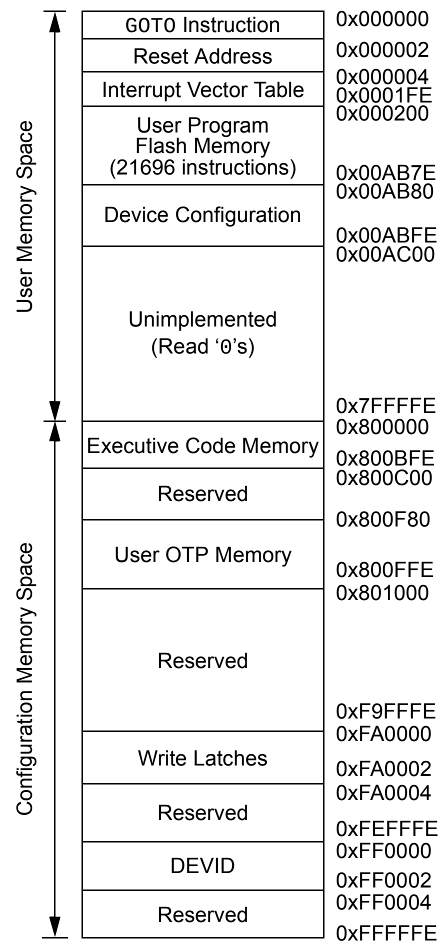
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev128gm002-i-so

FIGURE 4-2: PROGRAM MEMORY MAP FOR dsPIC33EV64GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

TABLE 4-45: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.4.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

> **Note:** For the `MOV` instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

> **Note:** Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.4.4 `MAC` INSTRUCTIONS

The dual source operand DSP instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MPY`, `MPY.N`, `MOVSAC` and `MSC`), also referred to as `MAC` instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set, {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must, therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

> **Note:** Register Indirect with Register Offset Addressing mode is available only for W9 (in X Data Space) and W11 (in Y Data Space).

In summary, the following addressing modes are supported by the `MAC` class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.4.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, `BRA` (Branch) instructions use 16-bit signed literals to specify the Branch destination directly, whereas the `DISI` instruction uses a 14-bit unsigned literal field. In some instructions, such as `ULNK`, the source of an operand or result is implied by the opcode itself. Certain operations, such as a `NOP`, do not have any operands.

5.0 FLASH PROGRAM MEMORY

> **Note 1:** This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EVXXXGM00X/10X family devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

The Flash memory can be programmed in the following three ways:

- In-Circuit Serial Programming™ (ICSP™)
- Run-Time Self-Programming (RTSP)
- Enhanced In-Circuit Serial Programming (Enhanced ICSP)

ICSP allows for a dsPIC33EVXXXGM00X/10X family device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (PGECx/PGEDx) lines, and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{\text{MCLR}}$). This allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

Enhanced ICSP uses an on-board bootloader, known as the Program Executive (PE), to manage the programming process. Using an SPI data frame format, the Program Executive can erase, program and verify program memory. For more information on Enhanced ICSP, refer to the specific device programming specification.

RTSP is accomplished using the `TBLRD` (Table Read) and `TBLWT` (Table Write) instructions. With RTSP, the user application can write program memory data as a double program memory word, a row of 64 instructions (192 bytes) and erase program memory in blocks of 512 instruction words (1536 bytes) at a time.

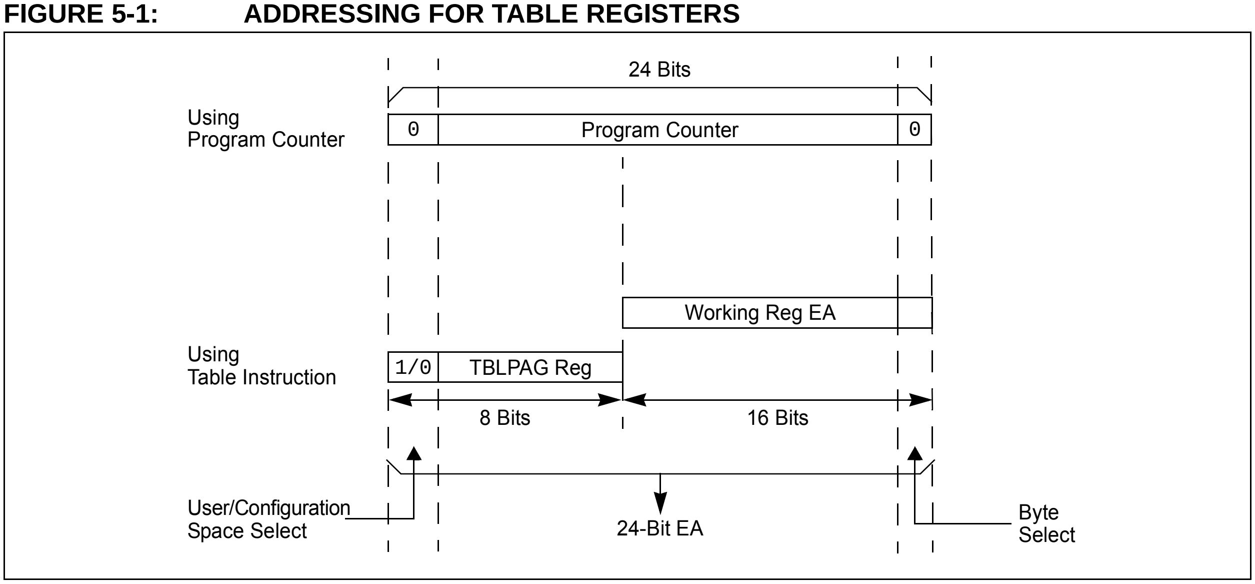
5.1 Table Instructions and Flash Programming

The Flash memory read and the double-word programming operations make use of the `TBLRD` and `TBLWT` instructions, respectively. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 5-1.

The `TBLRDL` and the `TBLWTL` instructions are used to read or write to bits<15:0> of the program memory. `TBLRDL` and `TBLWTL` can access program memory in both Word and Byte modes.

The `TBLRDH` and `TBLWTH` instructions are used to read or write to bits<23:16> of the program memory. `TBLRDH` and `TBLWTH` can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
ROI	DOZE2(3)	DOZE1(3)	DOZE0(3)	DOZEN(1,4)	FRCDIV2	FRCDIV1	FRCDIV0
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts will clear the DOZEN bit
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** Processor Clock Reduction Select bits(3)
111 = FCY divided by 128
110 = FCY divided by 64
101 = FCY divided by 32
100 = FCY divided by 16
011 = FCY divided by 8
010 = FCY divided by 4
001 = FCY divided by 2
000 = FCY divided by 1 (default)

bit 11 **DOZEN:** Doze Mode Enable bit(1,4)
1 = DOZE<2:0> field specifies the ratio between the peripheral clocks and the processor clocks
0 = Processor clock and peripheral clock ratio are forced to 1:1

bit 10-8 **FRCDIV<2:0>:** Internal Fast RC Oscillator Postscaler bits
111 = FRC divided by 256
110 = FRC divided by 64
101 = FRC divided by 32
100 = FRC divided by 16
011 = FRC divided by 8
010 = FRC divided by 4
001 = FRC divided by 2 (default)
000 = FRC divided by 1

bit 7-6 **PLLPOST<1:0>:** PLL VCO Output Divider Select bits (also denoted as 'N2', PLL postscaler)
11 = Output divided by 8
10 = Reserved
01 = Output divided by 4
00 = Output divided by 2

bit 5 **Unimplemented:** Read as '0'

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.
2: This register resets only on a Power-on Reset (POR).
3: DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.
4: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

11.4 Slew Rate Selection

The slew rate selection feature allows the device to have control over the slew rate selection on the required I/O pin which supports this feature. For this purpose, for each I/O port, there are two registers: SR1x and SR0x, which configure the selection of the slew rate. The register outputs are directly connected to the associated I/O pins, which support the slew rate selection function. The SR1x register specifies the MSb and the SR0x register provides the LSb of the 2-bit field that selects the desired slew rate. For example, slew rate selections for PORTA are as follows:

EXAMPLE 11-2: SLEW RATE SELECTIONS FOR PORTA

```
SR1Ax, SR0Ax = 00 = Fastest Slew rate
SR1Ax, SR0Ax = 01 = 4x slower Slew rate
SR1Ax, SR0Ax = 10 = 8x slower Slew rate
SR1Ax, SR0Ax = 11 = 16x slower Slew rate
```

11.5 Peripheral Pin Select (PPS)

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low pin count devices. In an application where more than one peripheral needs to be assigned to a single pin, inconvenient work arounds in application code, or a complete redesign, may be the only option.

The Peripheral Pin Select (PPS) configuration provides an alternative to these choices by enabling peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the device to their entire application, rather than trimming the application to fit the device.

The PPS configuration feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of most digital peripherals to any one of these I/O pins. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping after it has been established.

11.5.1 AVAILABLE PINS

The number of available pins is dependent on the particular device and its pin count. Pins that support the PPS feature include the designation, “RPn” or “RPIn”, in their full pin designation, where “n” is the remappable pin number. “RP” is used to designate pins that support both remappable input and output functions, while “RPI” indicates pins that support remappable input functions only.

11.5.2 AVAILABLE PERIPHERALS

The peripherals managed by the PPS are all digital only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer related peripherals (input capture and output compare) and Interrupt-on-Change (IOC) inputs.

In comparison, some digital only peripheral modules are never included in the PPS feature, because the peripheral’s function requires special I/O circuitry on a specific port and cannot be easily connected to multiple pins. These modules include I^2C and the PWM. A similar requirement excludes all modules with analog inputs, such as the ADC Converter.

A key difference between the remappable and non-remappable peripherals is that the remappable peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, the non-remappable peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

When a remappable peripheral is active on a given I/O pin, it takes priority over all the other digital I/O and digital communication peripherals associated with the pin. Priority is given regardless of the type of peripheral that is mapped. Remappable peripherals never take priority over any analog functions associated with the pin.

11.5.3 CONTROLLING PERIPHERAL PIN SELECT

The PPS features are controlled through two sets of SFRs: one to map the peripheral inputs and the other to map the outputs. Because they are separately controlled, a particular peripheral’s input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

The association of a peripheral to a peripheral-selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

11.5.4 INPUT MAPPING

The inputs of the PPS options are mapped on the basis of the peripheral. That is, a control register associated with a peripheral dictates the pin it will be mapped to. The RPINRx registers are used to configure peripheral input mapping (see Table 11-1 and Register 11-1 through Register 11-17). Each register contains sets of 8-bit fields, with each set associated with one of the remappable peripherals. Programming a given peripheral’s bit field with an appropriate 8-bit value maps the RPn pin with the corresponding value to that peripheral. For any given device, the valid range of values for any bit field corresponds to the maximum number of Peripheral Pin Selects supported by the device.

REGISTER 17-17: LEBDLYx: PWMx LEADING-EDGE BLANKING DELAY REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

REGISTER 22-15: CxBUFPNT4: CANx FILTERS 12-15 BUFFER POINTER REGISTER 4

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15BP3	F15BP2	F15BP1	F15BP0	F14BP3	F14BP2	F14BP1	F14BP0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F13BP3	F13BP2	F13BP1	F13BP0	F12BP3	F12BP2	F12BP1	F12BP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F15BP<3:0>:** RX Buffer Mask for Filter 15 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F14BP<3:0>:** RX Buffer Mask for Filter 14 bits (same values as bits 15-12)

bit 7-4 **F13BP<3:0>:** RX Buffer Mask for Filter 13 bits (same values as bits 15-12)

bit 3-0 **F12BP<3:0>:** RX Buffer Mask for Filter 12 bits (same values as bits 15-12)

REGISTER 24-1: ADxCON1: ADCx CONTROL REGISTER 1 (CONTINUED)

bit 7-5 **SSRC<2:0>:** Sample Clock Source Select bits

If SSRCG = 1:
111 = Reserved
110 = Reserved
101 = Reserved
100 = Reserved
011 = Reserved
010 = PWM Generator 3 primary trigger compare ends sampling and starts conversion
001 = PWM Generator 2 primary trigger compare ends sampling and starts conversion
000 = PWM Generator 1 primary trigger compare ends sampling and starts conversion

If SSRCG = 0:
111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = CTMU ends sampling and starts conversion
101 = Reserved
100 = Timer5 compare ends sampling and starts conversion
011 = PWM primary Special Event Trigger ends sampling and starts conversion
010 = Timer3 compare ends sampling and starts conversion
001 = Active transition on the INT0 pin ends sampling and starts conversion
000 = Clearing the Sample bit (SAMP) ends sampling and starts conversion (Manual mode)

bit 4 **SSRCG:** Sample Trigger Source Group bit

See SSRC<2:0> for details.

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)

In 12-Bit Mode (AD12B = 1), SIMSAM is Unimplemented and is Read as '0':
1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x) or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADCx Sample Auto-Start bit

1 = Sampling begins immediately after last conversion; SAMP bit is auto-set
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADCx Sample Enable bit

1 = ADCx Sample-and-Hold amplifiers are sampling
0 = ADCx Sample-and-Hold amplifiers are holding
If ASAM = 0, software can write '1' to begin sampling. Automatically set by hardware if ASAM = 1. If SSRC<2:0> = 000, software can write '0' to end sampling and start conversion. If SSRC<2:0> ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADCx Conversion Status bit[(1)]

1 = ADCx conversion cycle is completed.
0 = ADCx conversion has not started or is in progress
Automatically set by hardware when conversion is complete. Software can write '0' to clear DONE bit status (software not allowed to write '1'). Clearing this bit does NOT affect any operation in progress. Automatically cleared by hardware at the start of a new conversion.

Note 1: Do not clear the DONE bit in software if auto-sample is enabled (ASAM = 1).

25.1 Op Amp/Comparator Control Registers

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER

R/W-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
PSIDL	—	—	C5EVT(1)	C4EVT(1)	C3EVT(1)	C2EVT(1)	C1EVT(1)
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	C5OUT(2)	C4OUT(2)	C3OUT(2)	C2OUT(2)	C1OUT(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PSIDL:** Op Amp/Comparator Stop in Idle Mode bit
1 = Discontinues operation of all op amps/comparators when device enters Idle mode
0 = Continues operation of all op amps/comparators in Idle mode

bit 14-13 **Unimplemented:** Read as ‘0’

bit 12-8 **C5EVT:C1EVT:** Op Amp/Comparator 1-5 Event Status bits(1)
1 = Op amp/comparator event occurred
0 = Op amp/comparator event did not occur

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **C5OUT:C1OUT:** Op Amp/Comparator 1-5 Output Status bits(2)
When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.
2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
53	MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SS Wb,Ws,Acc	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,Ws,Acc	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Acc	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.US Wb,Ws,Acc	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.UU Wb,#lit5,Acc	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,Ws,Acc	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		MULW.SS Wb,Ws,Wnd	Wnd = signed(Wb) * signed(Ws)	1	1	None
		MULW.SU Wb,Ws,Wnd	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		MULW.US Wb,Ws,Wnd	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		MULW.UU Wb,Ws,Wnd	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.SU Wb,#lit5,Wnd	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb,#lit5,Wnd	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None
54	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
55	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
56	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
57	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
58	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
59	RCALL	RCALL Expr	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
60	REPEAT	REPEAT #lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
61	RESET	RESET	Software device Reset	1	1	None
62	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

FIGURE 30-17: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

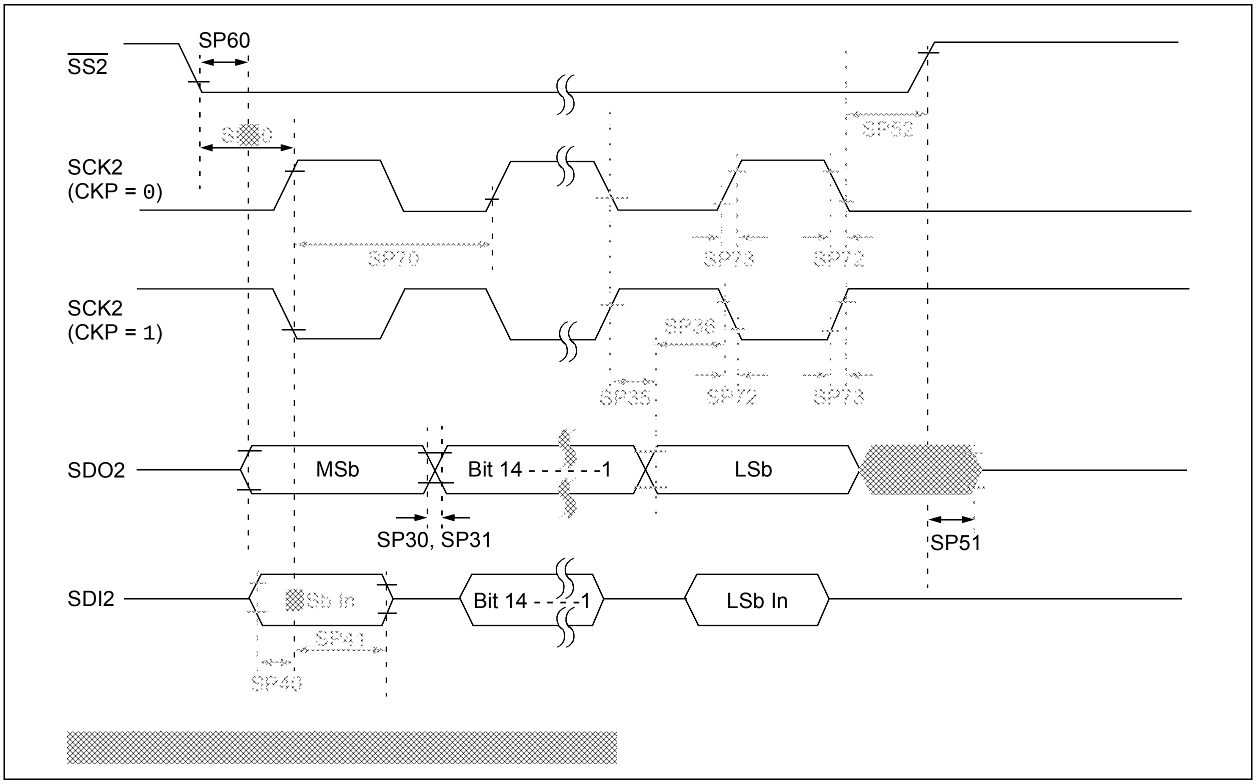


TABLE 30-57: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(4)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14	—	TAD	
AD56	FCNV	Throughput Rate	—	—	500	ksps	
AD57a	TSAMP	Sample Time when Sampling Any ANx Input	3	—	—	TAD	
AD57b	TSAMP	Sample Time when Sampling the Op Amp Outputs	3	—	—	TAD	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(1)	2	—	3	TAD	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(1)	2	—	3	TAD	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(1)	—	0.5	—	TAD	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(1)	—	—	20	µs	See **Note 3**

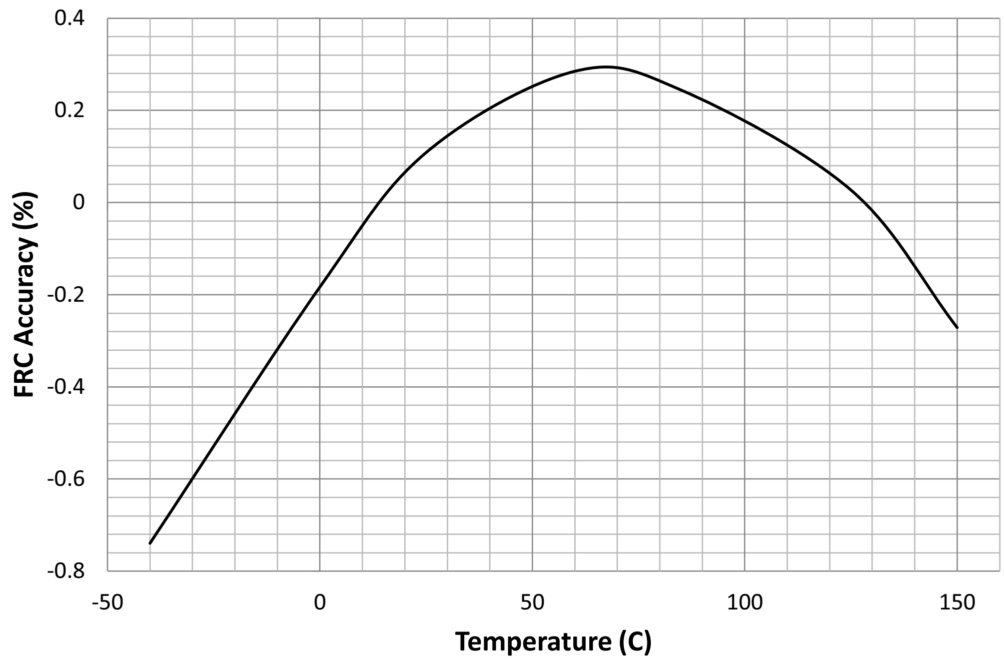
Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

2: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

3: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (ADxCON1<15>) = 1). During this time, the ADC result is indeterminate.

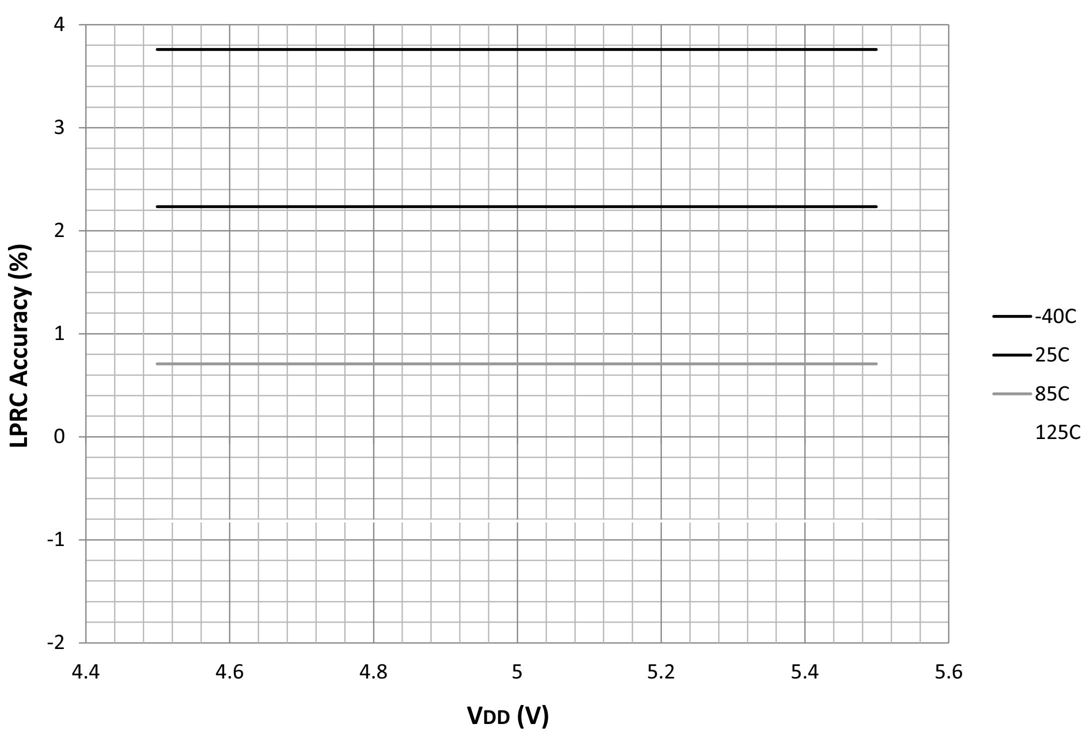
4: These parameters are characterized but not tested in manufacturing.

FIGURE 32-21: TYPICAL FRC ACCURACY vs. TEMPERATURE (5.5V VDD)



32.6 LPRC

FIGURE 32-22: TYPICAL LPRC ACCURACY vs. VDD



32.19 ADC Gain Offset Error

FIGURE 32-49: TYPICAL ADC GAIN ERROR vs. TEMPERATURE

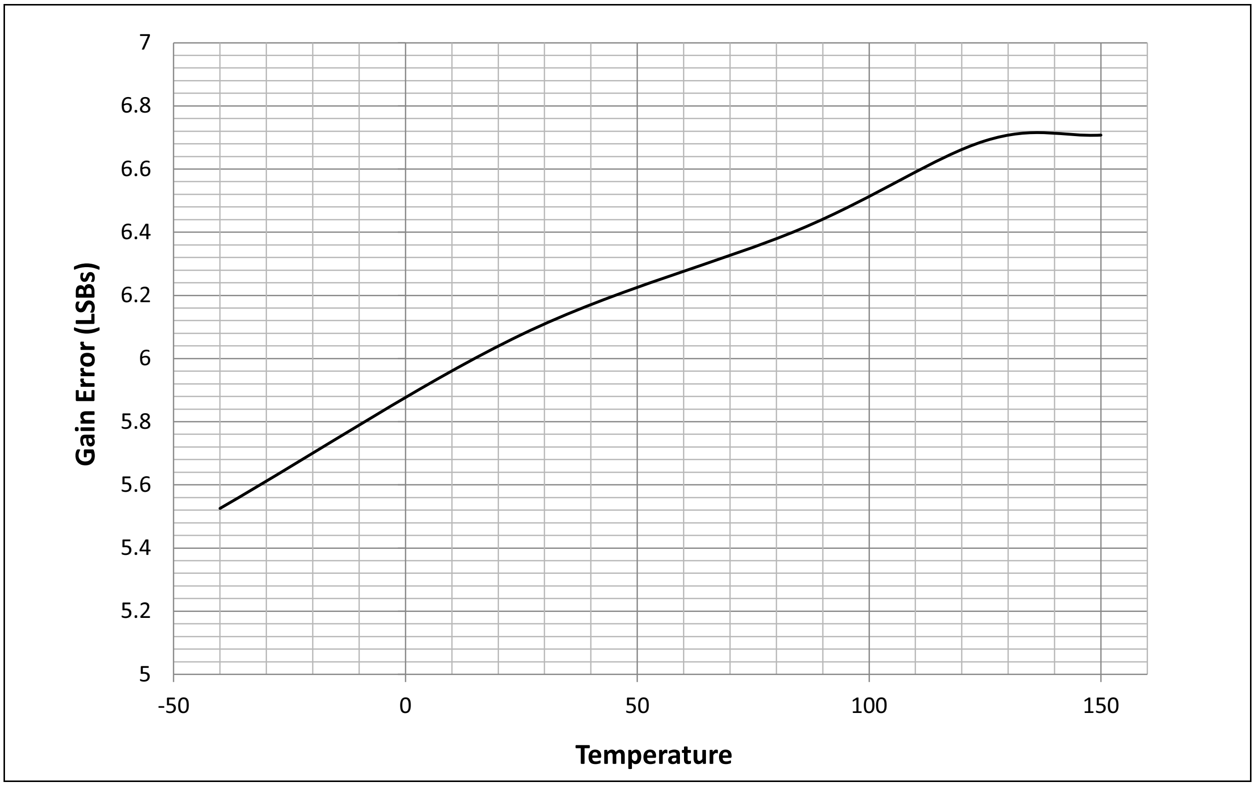


FIGURE 32-50: TYPICAL ADC OFFSET ERROR vs. TEMPERATURE

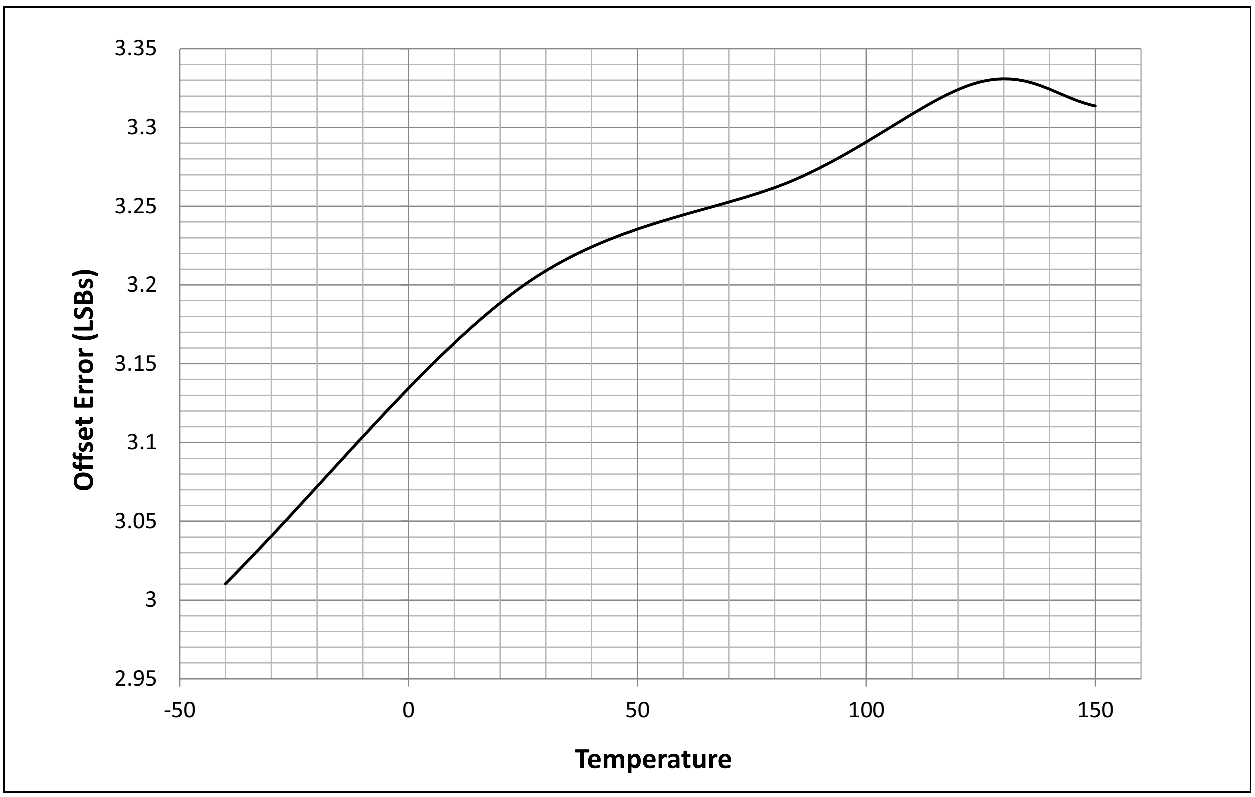
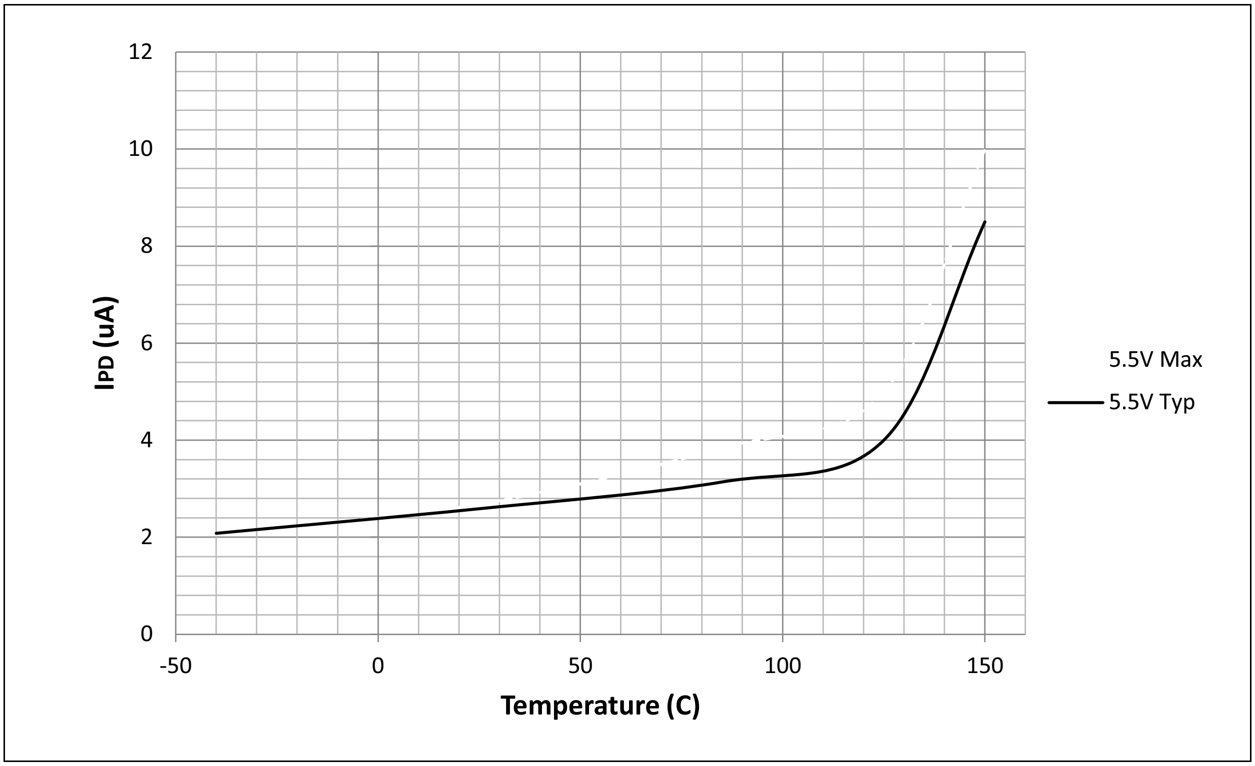


FIGURE 33-15: TYPICAL/MAXIMUM ΔIWDT vs. TEMPERATURE



33.5 FRC

FIGURE 33-16: TYPICAL FRC ACCURACY vs. VDD

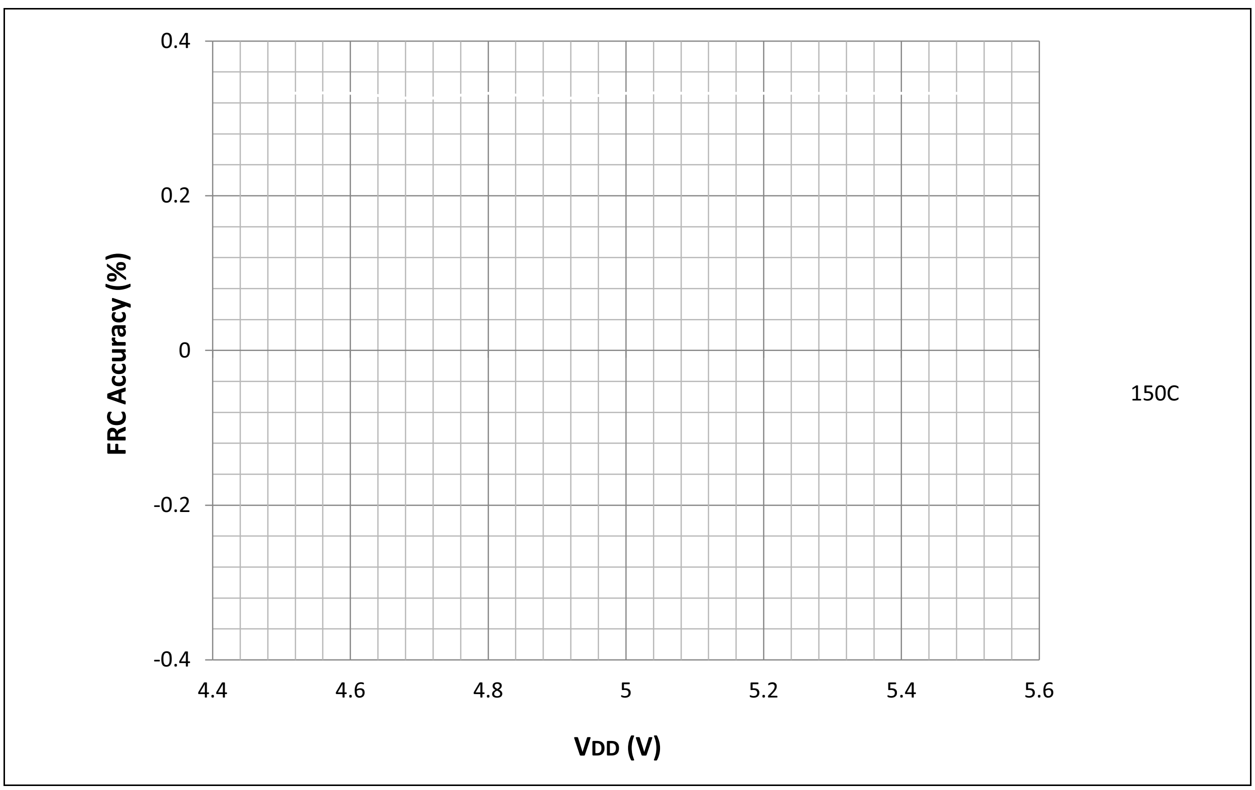
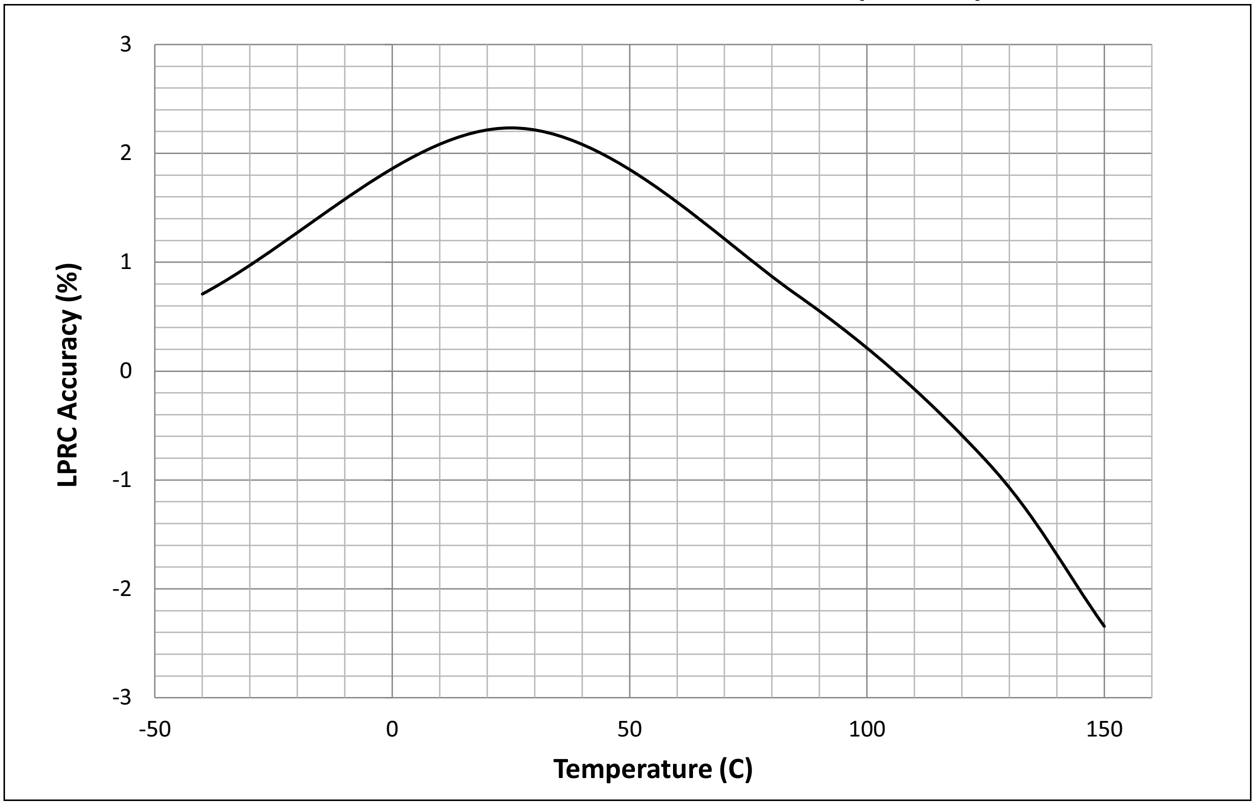
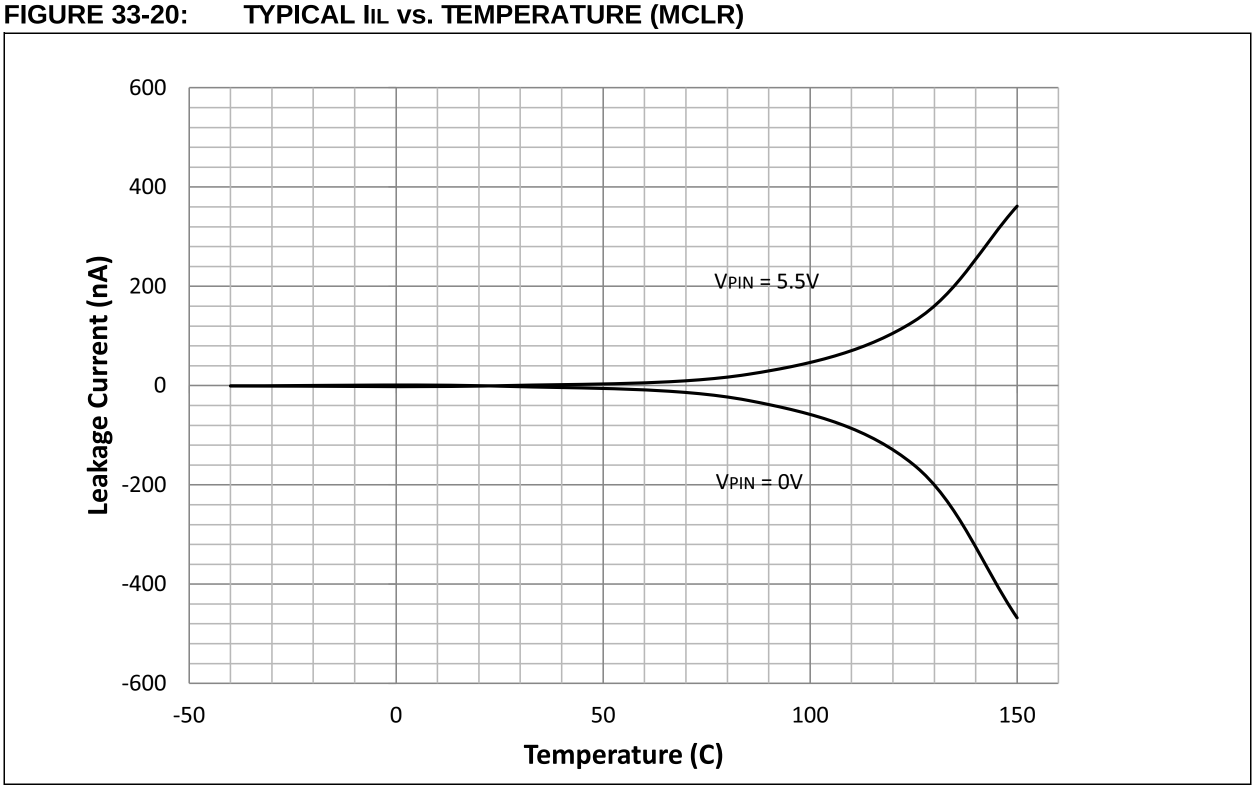


FIGURE 33-19: TYPICAL LPRC ACCURACY vs. TEMPERATURE (5.5V VDD)



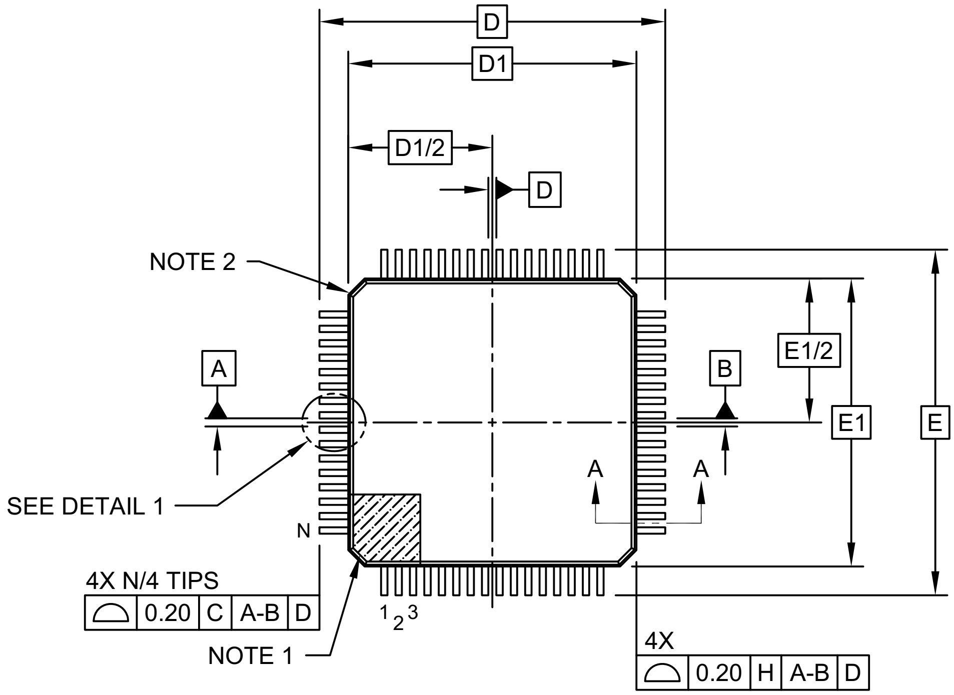
33.7 Leakage Current

FIGURE 33-20: TYPICAL IIL vs. TEMPERATURE ($\overline{\text{MCLR}}$)

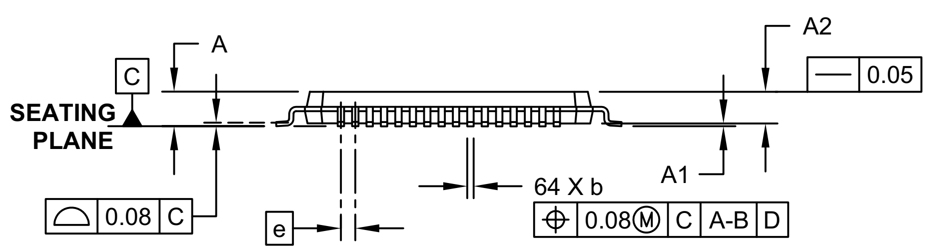


64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

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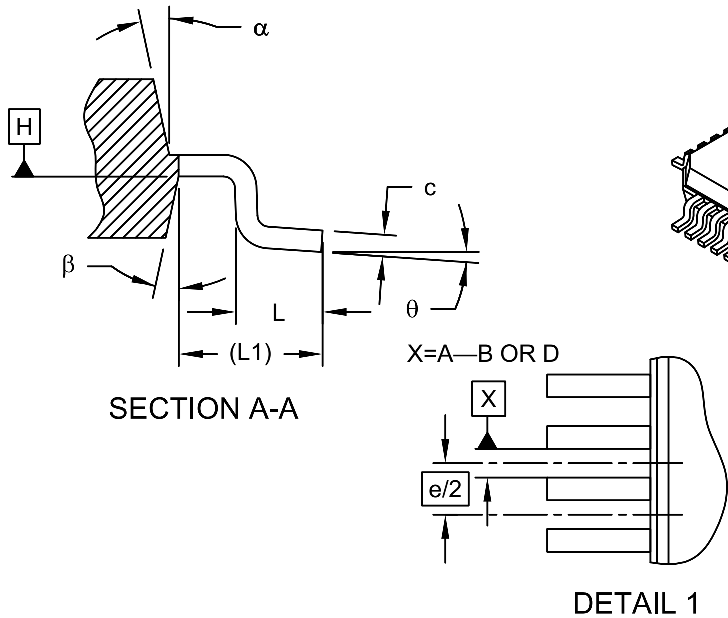
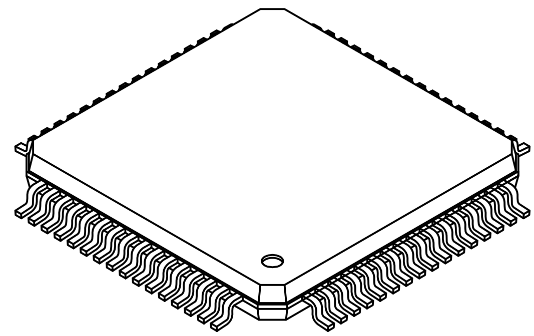
64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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